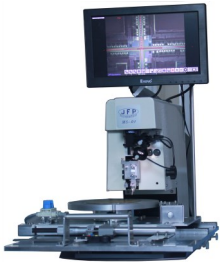


JFP Scriber



MS - 8"

**Manual
Scriber**

- High Accuracy

S-200 - 8"

Automatic Scriber

- Automated alignment
- X Y Theta

S-100 - 4"

Automatic Scriber-Breaker

- Clean facet
- Angle watch
- III-V Semi-Conductor



JFP Microtechnic activities are devoted in sales and services, integrated solutions for assembly, nano- microelectronic and optoelectronic.

Ergonomic, modular, accurate and easy to use, JFP equipments are in use all over the world, from Lab to Industry.

Support our customer's Projects and develop customized : our high skilled engineering team makes this possible !

***Customers, Solutions and
Quality are our top Priorities !***

JFP Microtechnic , an owner-managed company, with a strong reputation represents over 30 years of experience. The Company is based in Marcoussis, south of Paris.

JFP Microtechnic

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91460 Marcoussis - France

CONTACT :

Phone Number : +33 169 31 35 34
jfp@jfpmicrotechnic.com
www.jfpmicrotechnic.com



The machines which require minimal training to operate

JFP Product line

◇ **Wire Bonder**

- ⇒ WB100e-Wire Bonder
- ⇒ WB200e-Wire Bonder
- ⇒ MPT Mini Pull Tester

◇ **Pick & Place**

- ⇒ MPS-Manual Placer System
- ⇒ PP6 Universal Die Bonder
- ⇒ WB300-Ultrasonic Die Bonder
- ⇒ PP-One Pick & Place

◇ **Laser Bar**

- ⇒ PP-One-Laser Bar Test
- ⇒ Laser Bar Stacker-Unstacker

◇ **Diamond Scriber**

- ⇒ MS-Manual Scriber
- ⇒ S200-8 Scriber
- ⇒ S100-4 Scriber Breaker
- ⇒ SBS420 Scriber-Breaker-Sorter

Wire Bonder

Die Bonder

JFP PP-One Manual/Semi-automatic Micro Placer

JFP WB-100e Motorized Z-Axis Wedge & Ball Bonding



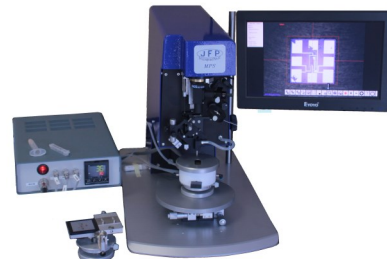
JFP WB-200e Semi-Automatic Wire Bonder Motorized Z - X/Y Axis Wedge & Ball Bonding

- Controlled loop
- Full manual mode
- Auto-bond mode
- Powerful Video Microscope



JFP MPS Manual Placer System for Lab

- Compact
- High Accuracy



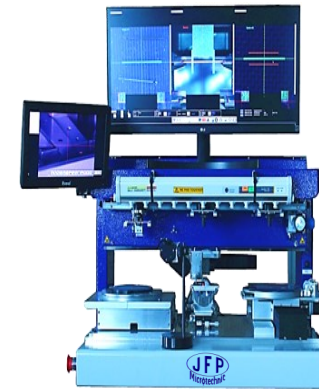
JFP PP6 Universal Die Bonder

- Full automated process
- Face up & Face down
- Placement of delicate devices



JFP WB300

- Z Automated process



Picking and Placement of :

- Delicate IC devices
- Laser Diodes /Sensors
- Micro-Mechanical Parts

Flexible Configuration

Laser Bar Stacker

Laser Bar Assembly

Laser Bar Test

- Die Bonding gluing and soldering of chips in pick and place operations

